

China 3D IC and 2.5D IC Packaging Market Research Report 2017

<https://marketpublishers.com/r/CAFEDE269DAEN.html>

Date: January 2017

Pages: 95

Price: US\$ 3,200.00 (Single User License)

ID: CAFEDE269DAEN

Abstracts

Notes:

Sales, means the sales volume of 3D IC and 2.5D IC Packaging

Revenue, means the sales value of 3D IC and 2.5D IC Packaging

This report studies 3D IC and 2.5D IC Packaging in China market, focuses on the top players in China market, with capacity, production, price, revenue and market share for each manufacturer, covering

Tezzaron

ASE Group

Amkor Technology

STATS ChipPAC Ltd.

Market Segment by Regions (provinces), covering

South China

East China

Southwest China

Northeast China

North China

Central China

Northwest China

Split by product Type, with production, revenue, price, market share and growth rate of each type, can be divided into

3D wafer-level chip-scale packaging

3D TSV

2.5D

Split by Application, this report focuses on consumption, market share and growth rate of 3D IC and 2.5D IC Packaging in each application, can be divided into

Consumer electronics

Telecommunication

Industrial sector

Automotive

Military and aerospace

Smart technologies

Medical devices

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